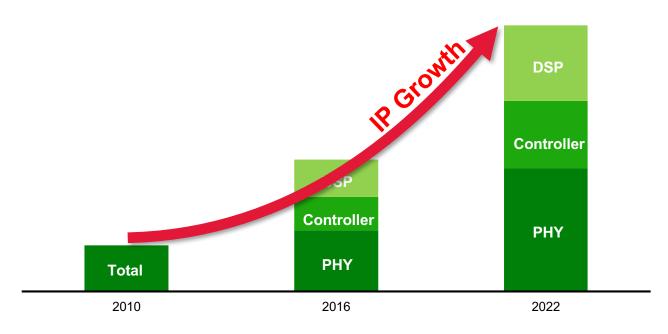


Dino Bekis, Vice President Marketing, IP Group Trusted Microelectronics Workshop February 2, 2017



Commercial IP Market Is Dramatically Expanding

>2X in 5 years!

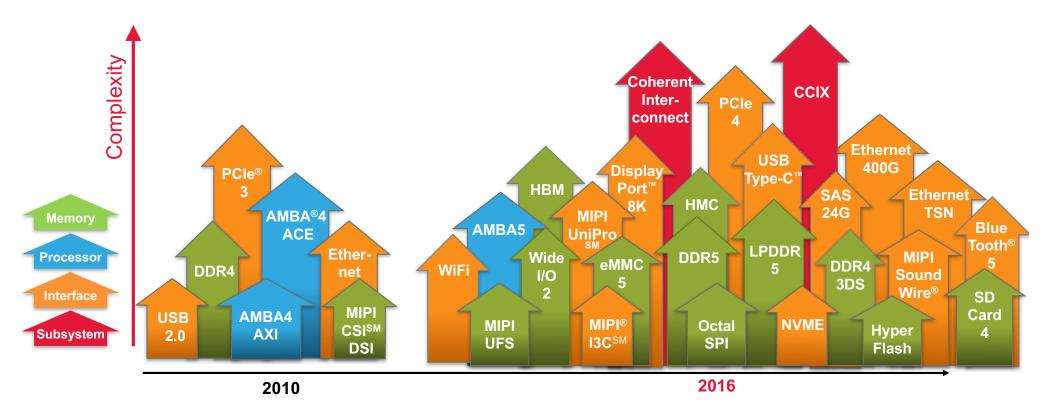


Sources: Press Releases, Magazines, Investor Presentations, Scientific Journals, Expert Interviews, and Market Analysis



New Standard Protocols Fuel Demand

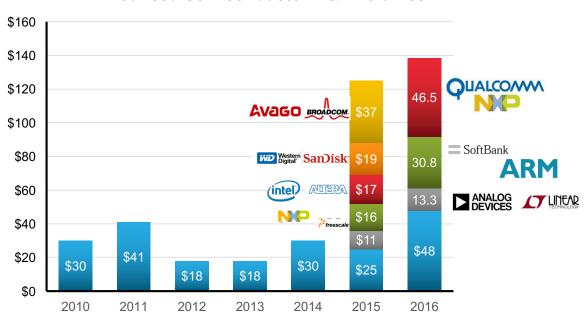
More complex, shorter life, narrower markets



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Consolidation Creates Expanding Need

Announced Semiconductor M&A Volumes



M&A Objectives:

- Reduced OPEX
- Accelerated TTM
- Greater innovation

Commercial IP aligns with M&A objectives

Source: Semiconductor Engineering http://semiengineering.com/the-urge-to-merge/ - Tom Stokes, Evercore, an investment banking advisory firm

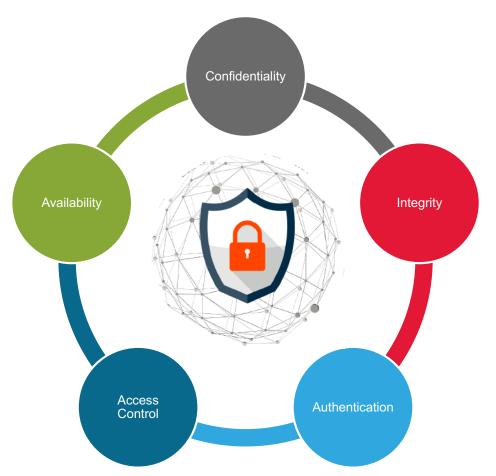


Business Imperatives for Commercial IP

- Focus limited engineering resources on differentiating technology
 - Apply most valuable resources on highest value-add content
 - Expand technical capabilities beyond current staff, improve OPEX leverage
- Access to new technologies with reduced first-adopter risks
 - Silicon-proven technology in leading-edge nodes
 - Deep engagement and leadership with standards bodies
- Faster time-to-market
 - Established software ecosystem
 - 3rd-party IP integration experience
- Leverage the knowledge of 100s of customers, 1000s of designs
 - Multiple markets exposure, broad interoperability
 - Production-hardened, trusted solution



Five Pillars of Security



Confidentiality

 Protection against access secret data/code via encryption

Integrity

 Protection against modification of data/code/system state

Authentication

 Protection against forged identity in illegal communication or operation

Access Control

 Protection against unauthorized usage of resource or operation

Availability

 Protection against malicious depletion of resource from normal usage



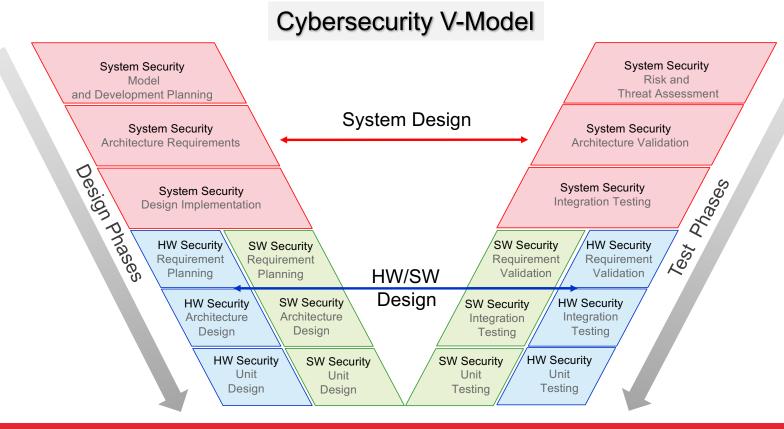
Emerging Needs and Challenges for Secure Silicon

- Secure software engineering process well established in tier-1 companies
 - e.g., Microsoft SDL
- Some segments have established practice due to regulation
 - e.g., smartcard/POS for finance/payment, Common Criteria
- Demand in industry segments handling mission/safety-critical tasks
 - e.g. IoT infrastructure, automotive, aerospace
- No pan-industry standard practice for silicon development
 - Broad range of metric-driven signoff
 - Deeper cycles, high value bugs, increasingly large designs



Combined Security and Safety in Automotive

Secure engineering process similar to ISO 26262 functional safety

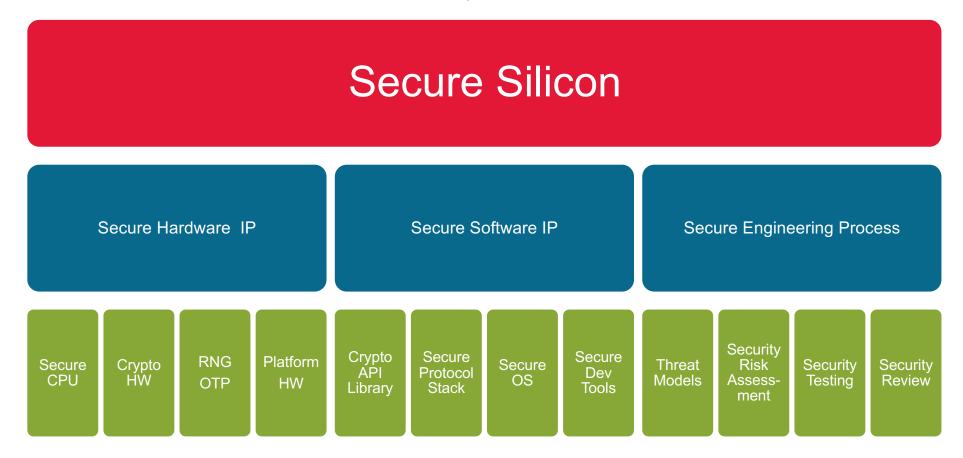


SAE J3061 defines security practice V-model similar to ISO 26262 model on safety



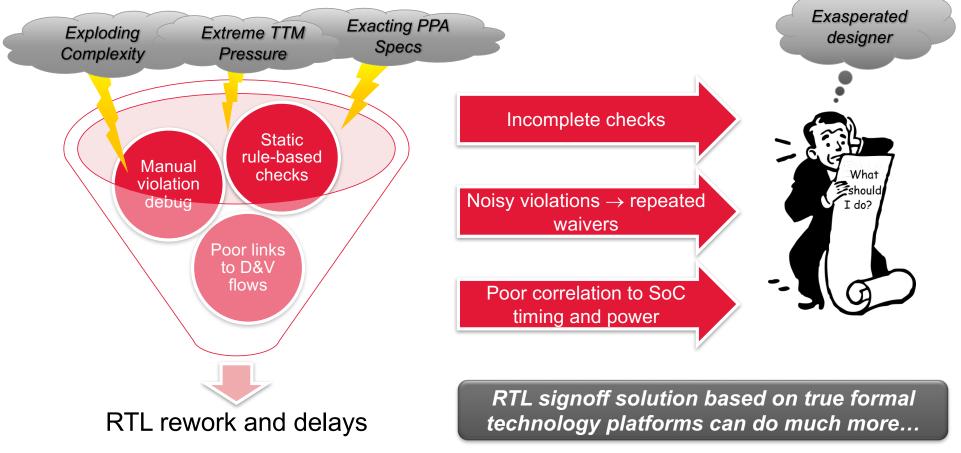
Secure Semiconductor Products

Secure silicon = hardware + software + process





Many RTL Signoff Solutions Lack Formal Intelligence



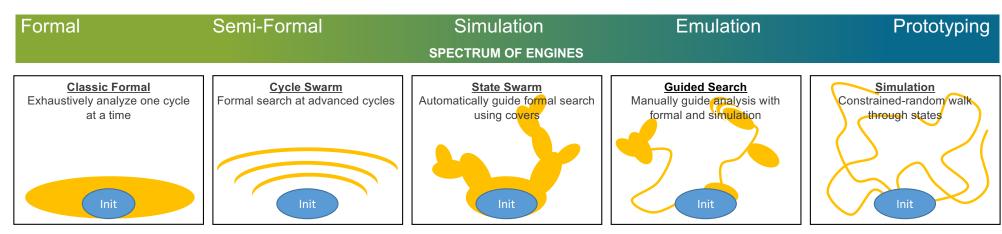


Trusted, Assured, Secured

Towards a comprehensive, practical solution

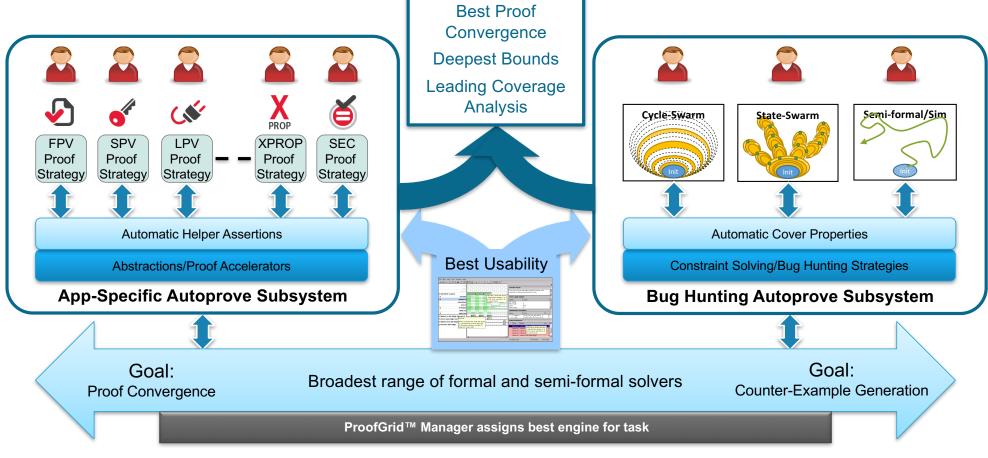
- Interrelated requirements
 - Evolving threat vectors
 - No silver bullet
 - Requires coordinated orchestration of multiple methods
- Cadence: Rich set of foundational assets
 - · Algorithms, heuristics
 - Tools, flows
 - Experience, expertise

- Innovation progression
 - · Analysis methods
 - Metrics
 - Transformations
 - Optimizations



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JasperGold Apps: Ease-of-Use, High Capacity, and Performance





Tensilica Processor IP

Leadership scalability, power, performance, and area



IoT, Mobile, Automotive, Storage, Networking, Video/Imaging, Printers, Security...

Xtensa® DSP

Foundation of all Tensilica® processors

Targeted Market Vertical DSP Solutions

















Vision DSP

- Image processing and analytics
- Vision processing
- Convolutional Neural **Networks**

Custom



Application Specific

Xtensa

IoT. **Multi-Purpose**

Fusion DSP

- Scalable DSP
- Always-alert
- Sensor processing
- Comms/security

HiFi DSP

Audio, Voice,

Speech

- Encode and decode
- Voice trigger
- Noise reduction
- Post-processing
- 170+ codecs

ConnX DSP

Wireless

Communications

- Narrow to wide-band LTE/LTE-A, WiFi, **Smart Grid**
- Infrastructure and terminals

Tensilica Optimization Platform

Common Development Tools and Broad 3rd-Party Ecosystem

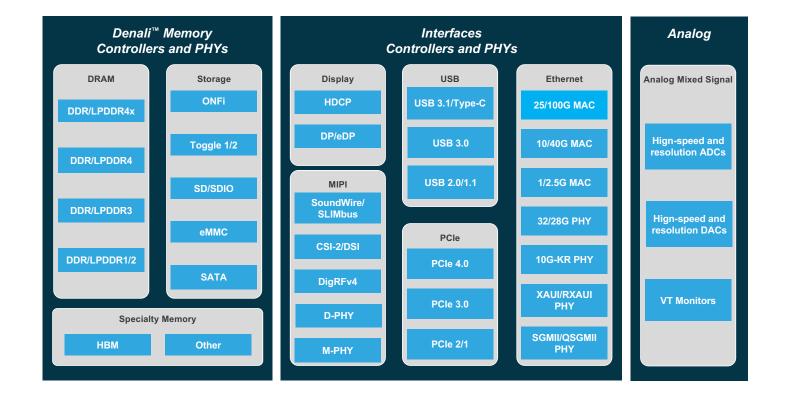
4B+ Cores per Year

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Thousands of designs

Cadence Design IP Portfolio

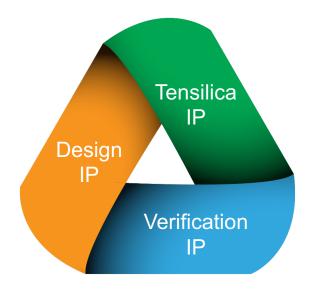
Broad and growing set of solutions for your next SoC





Cadence IP – Build the Future Faster

Unleashing your creativity to architect, integrate, and verify leading-edge SoCs



Faster time to market. highly differentiated products

- CNN-, vision-, and audio-optimized solutions
- Low-power embedded DSP platform
- Rapid, verified generation/configuration
- Latest protocol IP, including DDR, PCIe
- Silicon proven in the most popular process nodes
- High quality through multi-dimensional verification
- Consistently first to market with the right protocols
- Complete and comprehensive tools
- Work with any language or methodology





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